

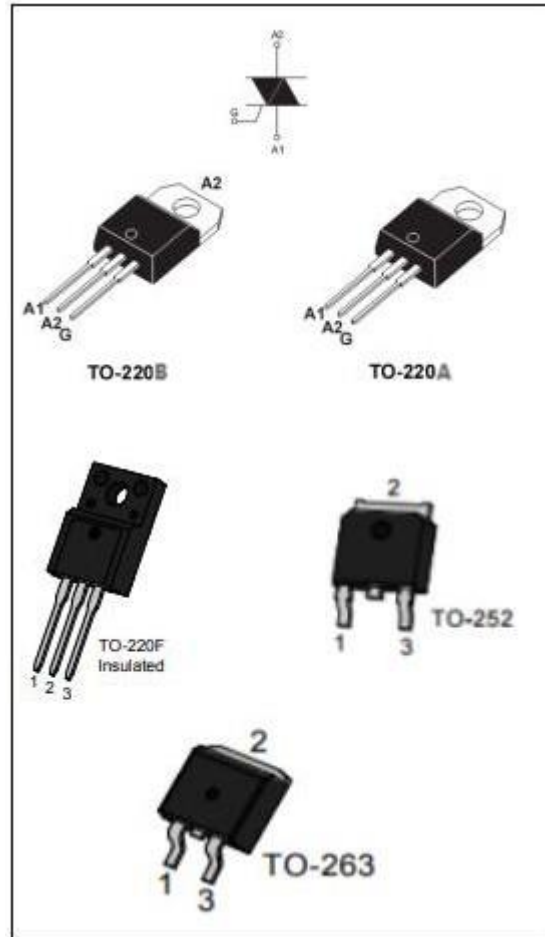


● Product features and main applications:

NPNPN five-layer structure of silicon bidirectional devices; with independent intellectual property rights of single-sided digging technology, table glass passivation process; multi-layer metallized electrodes on the back; with high blocking voltage and high temperature stability.

Mainly used in:

vacuum cleaners, power tools and other motor speed controllers; solid state relays; heating controllers (temperature regulation); other phase control circuits.



● Characteristics

Table 1. Absolute maximum ratings ($T_j = 25^\circ\text{C}$ unless otherwise stated)

Symbol	Parameter name		value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	BTA BTB	$T_c=80^\circ\text{C}$ $T_c=90^\circ\text{C}$	4 A
I_{TSM}	Non repetitive surge peak on-state current (full cycle, T_j initial = 25°C)	F=50HZ tp=20ms		25 A



I^2t	I ² t value for fusing	$t_p=10ms$	3.1	A ² S	
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \leq 100 \text{ ns}$	$T_j=125^\circ\text{C}$	50	A/us	
V_{DRM}/V_{RRM}	Off state repetitive peak voltage Reverse repetitive peak voltage	$T_j=25^\circ\text{C}$	600/800	V	
I_{GM}	Peak gate current	$t_p=20\mu s$	$T_j=150^\circ\text{C}$	4	A
$P_{G(AV)}$	Average gate power dissipation	$T_j=150^\circ\text{C}$	0.5	W	
T_{stg} T_j	Storage junction temperature range Operating junction temperature range		-40to+150 -40to+125	$^\circ\text{C}$	

● Table 2. Electrical characteristics ($T_j = 25^\circ \text{C}$, unless otherwise specified) -- 3 quadrants

Symbol	Name and test conditions	Quadrant	Range	value	Unit
I_{GT}	$V_D=12V \quad R_L=100\Omega$	I II III	MAX	≤ 10	mA
V_{GT}			MAX	1.5	V
V_{GD}			MIN	0.2	V
I_H	$I_T = 100 \text{ mA}$		MAX	25	mA
I_L	$I_G = 1.2 \times I_{GT}$		MAX	35	mA
dv/dt	$V_D = 67\% V_{DRM}$, gate open, $T_j = 125^\circ \text{C}$		MIN	200	V/us
(dv/dt) _c	Critical rise rate of commutation voltage $T_J = 150^\circ \text{C}$		MIN	10	V/us



● **Table 3. Electrical characteristics (T_j = 25 ° C, unless otherwise specified) - Standard Triac (4 quadrants)**

Symbol	Name and test conditions	Quadrant	Range	value		Unit
I _{GT}	V _D =12V R _L =100 Ω	I II III IV	MAX	I、II、III	IV	mA
				≅ 10	≅ 25	
V _{GT}	MAX		1.5		V	
V _{GD}	VD = VDRM, RL = 3.3 kΩ, T _j = 125 ° C		MIN	0.2		V
I _H	I _T =500mA		MAX	50		mA
I _L	IG = 1.2 x IGT		MAX	30		mA
				50		
dv/dt	VD = 67% VDRM, gate open, T _j = 125 ° C		MIN	200		V/us
(dv/dt) _c	Critical rise rate of commutation voltage T _J = 150 ° C		MIN	10		V/us

● Static parameters

Symbol	Parameter name			value	Unit
V _{TM}	I _{TM} = 5A	T _j =25°C	MAX	1.60	V
V _{TO}	threshold on-state voltage	T _j =150°C	MAX	0.92	V
R _d	Dynamic resistance	T _j =150°C	MAX	36.6	m Ω
I _{IDRM} I _{IRRM}	VDRM = VRRM	T _j =25°C	MAX	5	uA
		T _j =150°C		1	mA
R _{th(j-c)}	Junction to ambient	BTA		2.05	°C/W
		BTB		1.25	



● BT136 characteristic curve

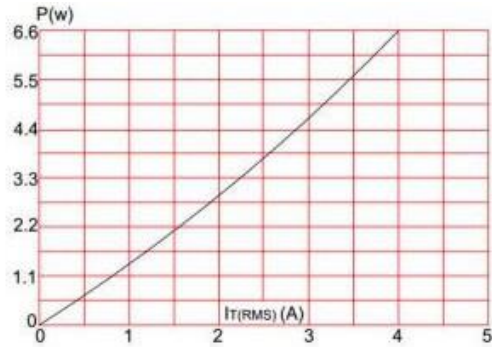


FIG.1: Maximum power dissipation versus RMS on-state current

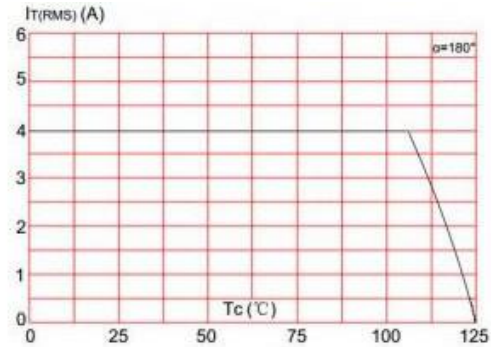


FIG.2: RMS on-state current versus case temperature

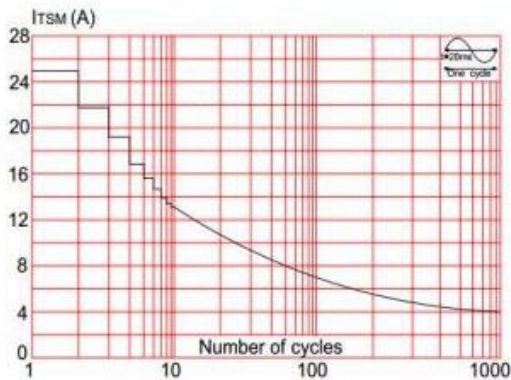


FIG.3: Surge peak on-state current versus number of cycles

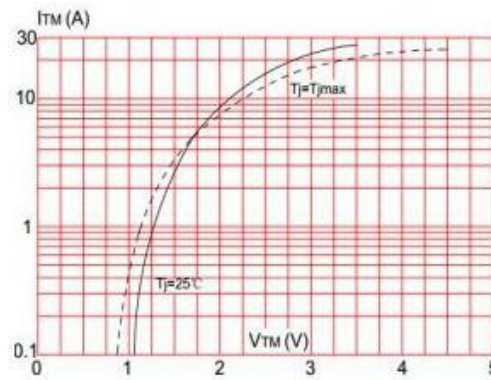


FIG.4: On-state characteristics (maximum values)

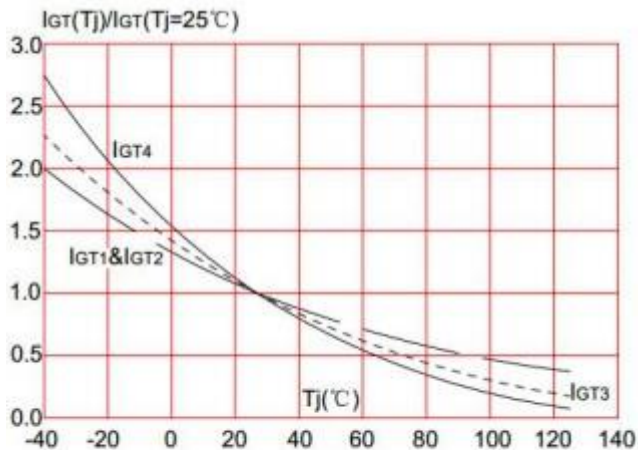
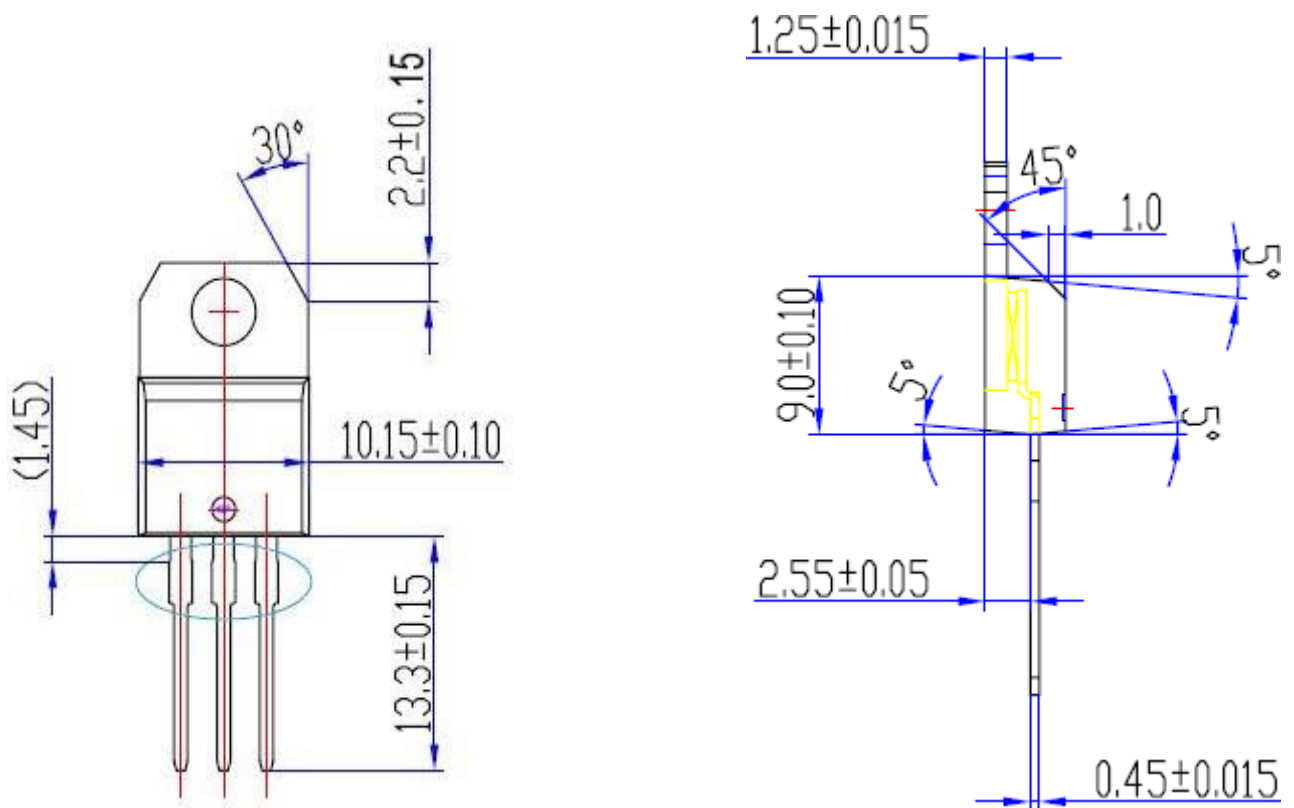


FIG.5: Relative variations of gate trigger current, holding current and latching current versus junction temperature



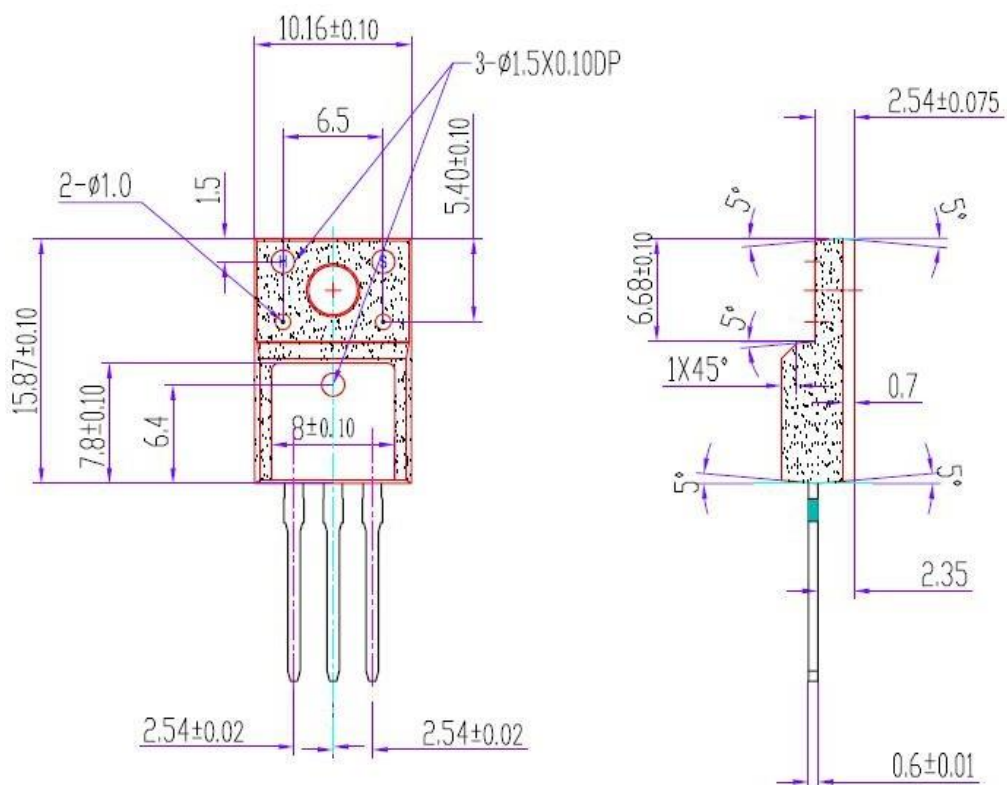
● TO-220 Dimensional drawing:

Unit: mm (± 0.1)



● TO-220F Dimensional drawing:

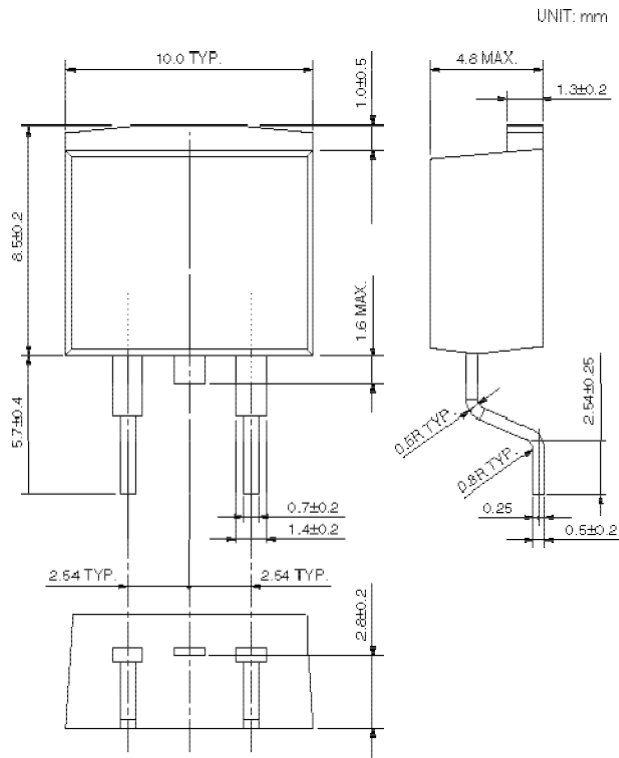
Unit: mm (± 0.1)



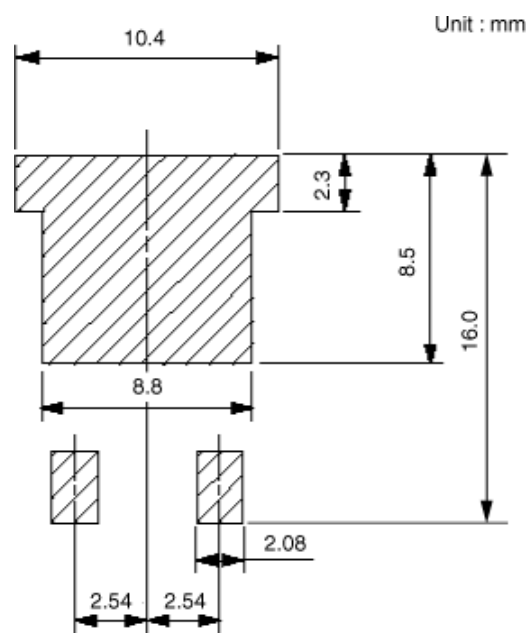


● TO-263 Dimensional drawing:

Unit: mm (± 0.1)



: The area without solder plated



● T0-252 Dimensional drawing:

Unit: mm (± 0.1)

